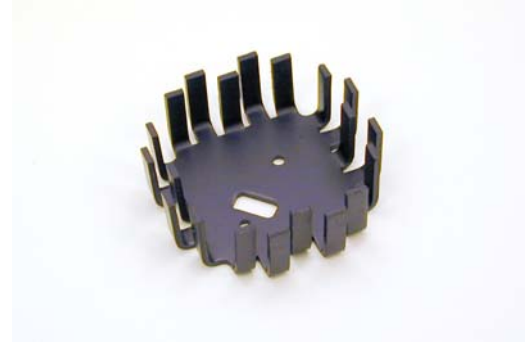
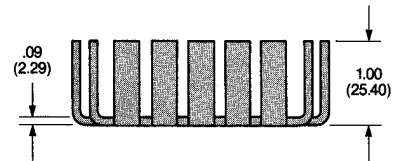
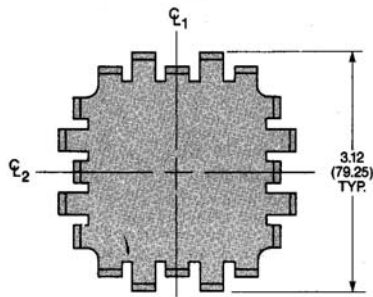


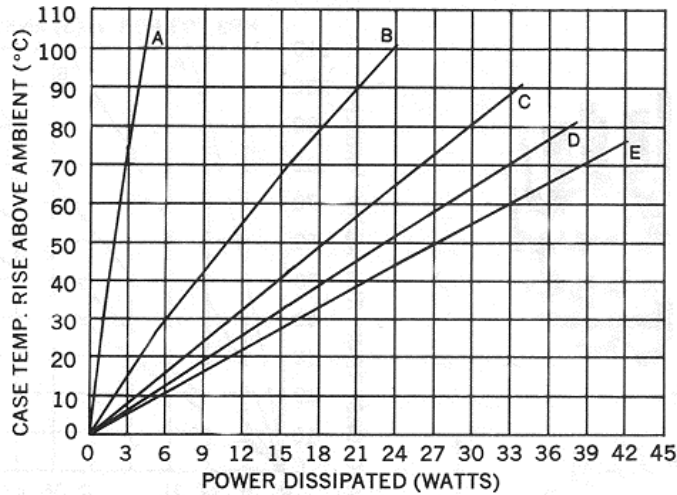
METAL CASE, CASE-MOUNTED SEMICONDUCTORS



HP3 Series for Single TO-3 or Stud Mount



HP3-T03-CB w/2N3055 (TO-3) TRANSISTOR



DESCRIPTION OF CURVES

- A. N.C. Horiz. Device Only Mounted to G-10.
- B. N.C Horiz. & Vert. With Dissipator.
- C. 200 FPM w/Diss.
- D. 500 FPM w/Diss.
- E. 1000 FPM w/Diss.

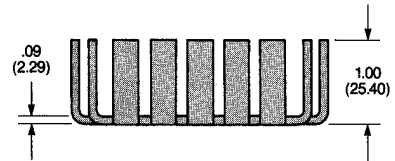
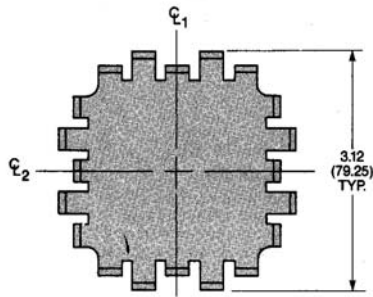
- Thermal Resistance Case to Sink is 0.1-0.3 °C/W w/Joint Compound.
- Derate 1.0 °C/watt for unplated part in natural convection only.

Ordering Information

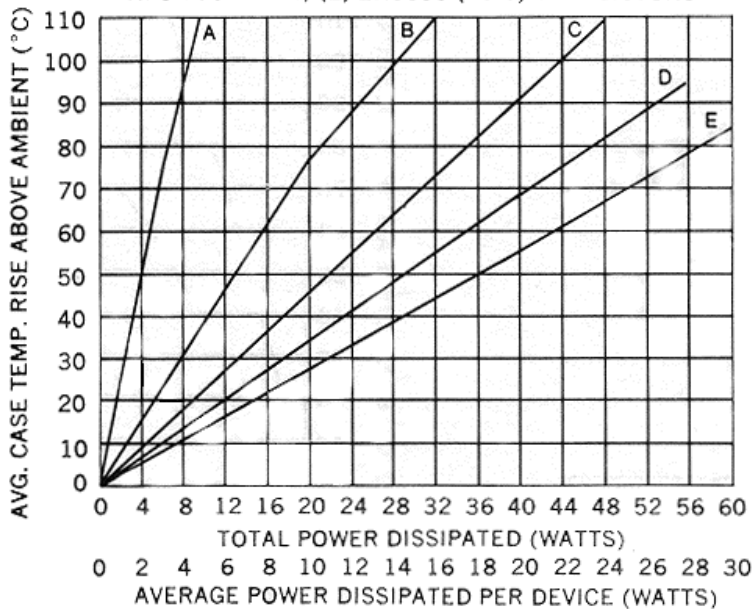
| CTS IERC PART NO. | | | Semiconductor Accommodated | Hole patt. ref. no. | Max. Weight (Grams) |
|-------------------|-----------------------|--------------------|----------------------------|---------------------|---------------------|
| Unplated | Comm'l. Black Anodize | Mil. Black Anodize | | | |
| HP3-000-U | HP3-000-CB | HP3-000-B | Undrilled | -- | 55.0 |
| HP3-T03-U | HP3-T03-CB | HP3-T03-B | T0-3 | 16 | 55.0 |
| HP3-T03-33U | HP3-T03-33CB | HP3-T03-33B | T0-3 IC | 17 | 55.0 |

| | | | | | |
|-------------|--------------|-------------|------------------|----|------|
| HP3-T03-44U | HP3-T03-44CB | HP3-T03-44B | T0-3 PANEL MOUNT | 31 | 55.0 |
| HP3-436-U | HP3-436-CB | HP3-436-B | T0-3 (4 PIN) | 18 | 55.0 |
| HP3-T015-U | HP3-T015-CB | HP3-T015-B | T0-15, D0-5 | 23 | 55.0 |
| HP3-T06-U | HP3-T06-CB | HP3-T06-B | T0-6, T0-36 | 19 | 55.0 |
| HP3-420-U | HP3-420-CB | HP3-420-B | UNIVERSAL | 27 | 55.0 |

HP3 for Dual TO-3 Outline



HP3-T03-4CB w/(2) 2N3055 (TO-3) TRANSISTORS



DESCRIPTION OF CURVES

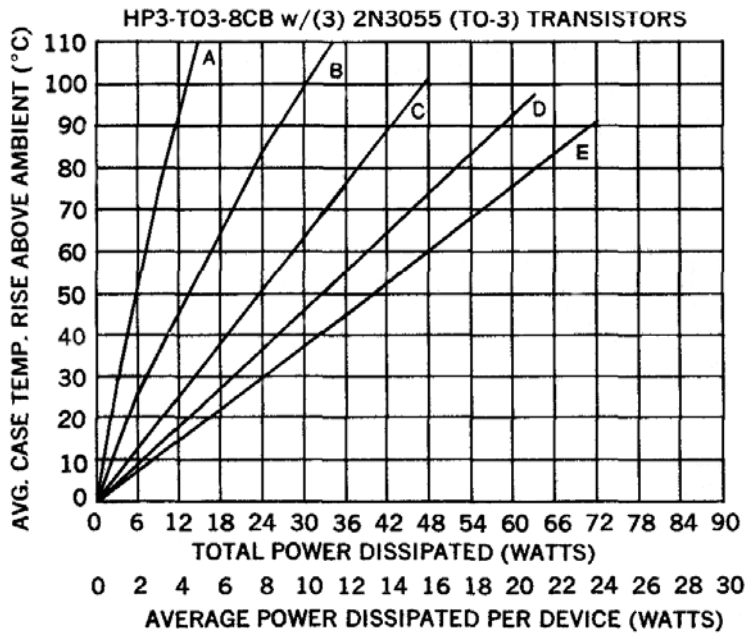
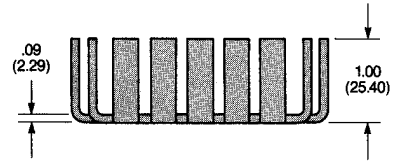
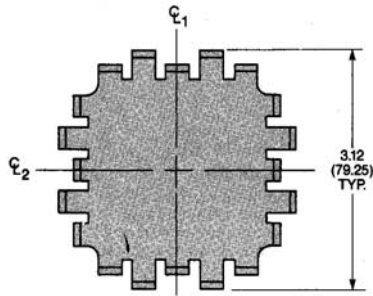
- A. N.C. Horiz. Device Only Mounted to G-10.
- B. N.C Horiz. & Vert. With Dissipator.
- C. 200 FPM w/Diss.
- D. 500 FPM w/Diss.
- E. 1000 FPM w/Diss.

- Thermal Resistance Case to Sink is 0.1-0.3 °C/W w/Joint Compound.
- Derate 2.0 °C/watt for unplated part in natural convection only.

Ordering Information

| CTS IERC PART NO. | | | Semiconductor Accommodated | Hole patt. ref. no. | Max. Weight (Grams) |
|-------------------|-----------------------|--------------------|----------------------------|---------------------|---------------------|
| Unplated | Comm'l. Black Anodize | Mil. Black Anodize | | | |
| HP3-T03-4U | HP3-T03-4CB | HP3-T03-4B | Two TO-3s | 6 | 55.0 |
| HP3-437-U | HP3-437-CB | HP3-437-B | Two TO-3s (4 pin) | 12 | 55.0 |

HP3 for Three TO-3 Outline



DESCRIPTION OF CURVES

- A. N.C. Horiz. Device Only Mounted to G-10.
- B. N.C Horiz. & Vert. With Dissipator.
- C. 200 FPM w/Diss.
- D. 500 FPM w/Diss.
- E. 1000 FPM w/Diss.

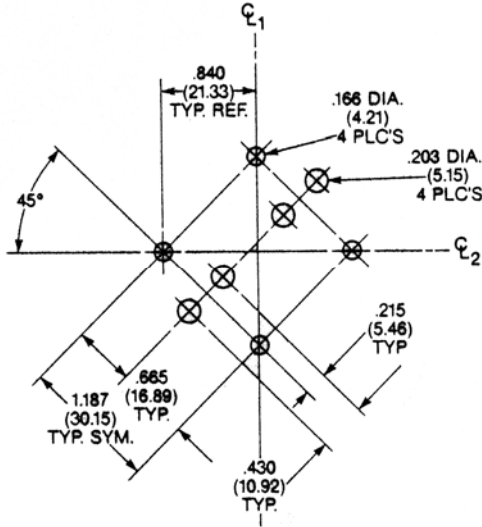
- Thermal Resistance Case to Sink is 0.1-0.3 °C/W w/Joint Compound.
- Derate 3.0 °C/watt for unplated part in natural convection only.

Ordering Information

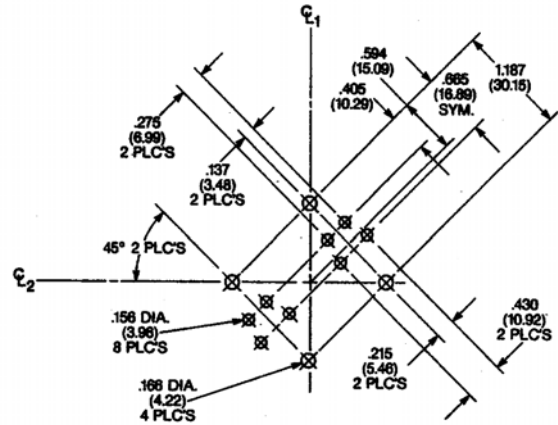
| CTS IERC PART NO. | | | Semiconductor Accommodated | Hole patt. ref. no. | Max. Weight (Grams) |
|-------------------|-----------------------|--------------------|----------------------------|---------------------|---------------------|
| Unplated | Comm'l. Black Anodize | Mil. Black Anodize | | | |
| HP3-T03-8U | HP3-T03-8CB | HP3-T03-8B | Three TO-3s | 13 | 55.0 |

HOLE PATTERNS

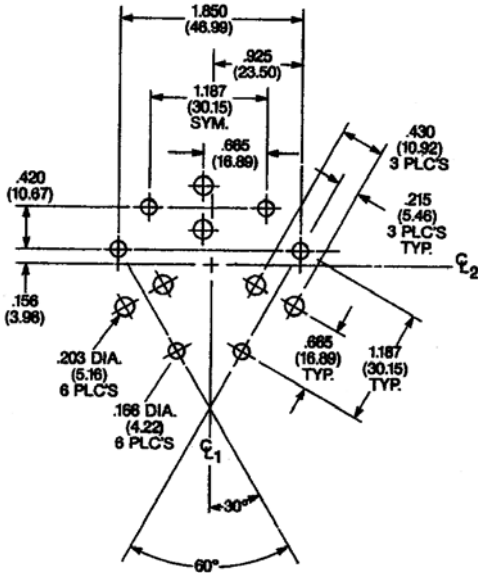
6. Hole pattern no. 124 accomodates two TO-3s. Available in HP3 series heat dissipators only.



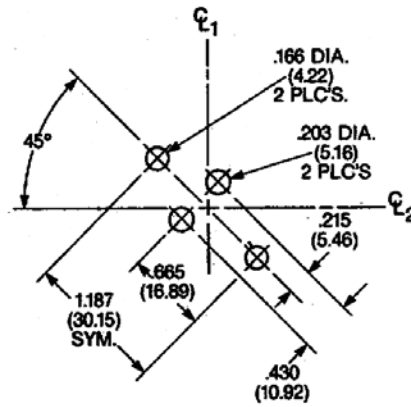
12. Hole pattern no. 437 accomodates two TO-3s (4-pin). Available in HP3 series heat dissipators only.



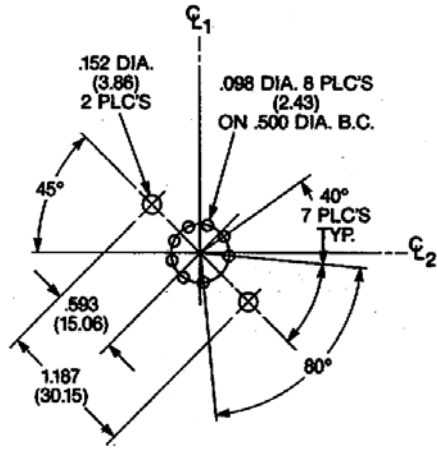
13. Hole pattern no. 186 accomodates three TO-3s. Available in HP3 series heat dissipators only.



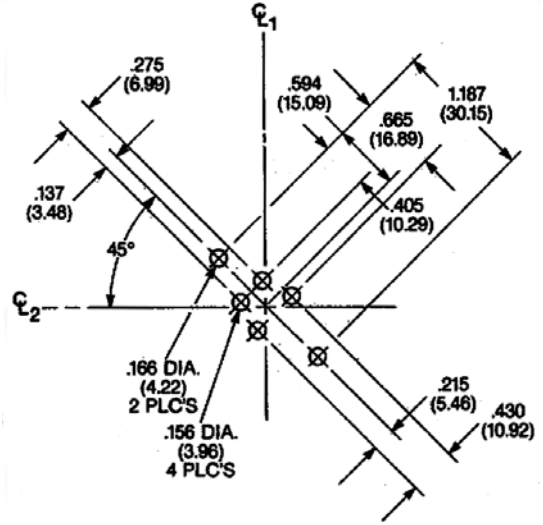
16. Hole pattern no. 1 accomodates T0-3s. Available in UP, UP1, UP2, HP1, and HP3 series heat dissipators.



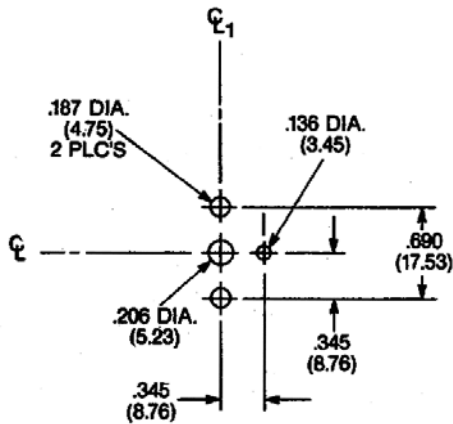
17. Hole pattern no. 202 accommodates T0-3 ICs. Available in UP, UP1, UP2, HP1, and HP3 series heat dissipators.



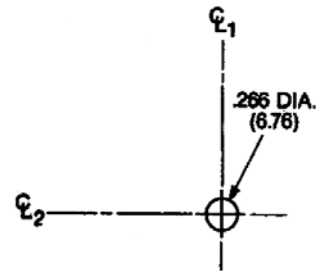
18. Hole pattern no. 436 accommodates T0-3s (4-pin). Available in UP, UP1, UP2, HP1, and HP3 series heat dissipators.



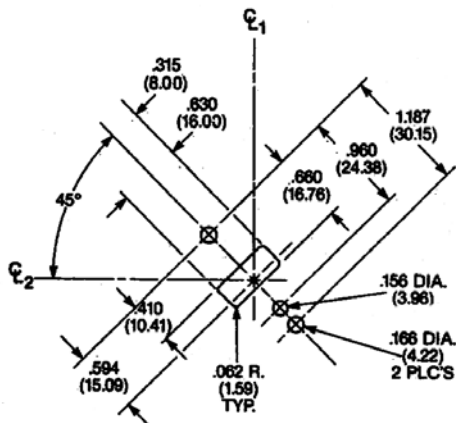
19. Hole pattern no. 2 accommodates T0-6s or T0-36s. Available in UP, UP1, UP2, HP1, and HP3 series heat dissipators.



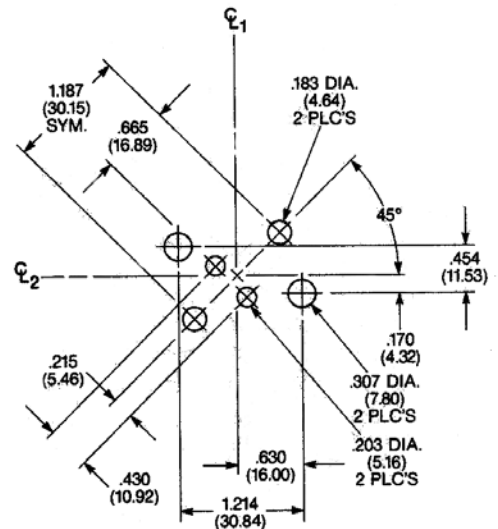
23. Hole pattern no. 3 accommodates T0-15s, D0-5s and other 1/4" stud mount devices. Available in UP, UP1, UP2, HP1, and HP3 series heat dissipators.



27. Hole pattern no. 420 (Universal) accommodates T0-3s, T0-66s, T0-126s, T0-127s, or T0-220s. Available in UP, UP1, UP2, HP1, and HP3 series heat dissipators.



31. Hole pattern no. 213 accommodates one TO-3 (panel mounted). Available in HP1 and HP3 series heat dissipators only.



CTS IERC, Heat Sinks and Thermal Management Solutions

413 North Moss Street, Burbank, California 91502 Tel: (818) 842-7277 Fax: (818) 848-8872

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